

**Product End-of-Life Disassembly Instructions**
**Product Category:** **Servers**
**Marketing Name / Model**  
[List multiple models if applicable.]

HPE Compute Scale-up Server 3200

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPE products to remove components and materials requiring selective treatment, as defined by Directive 2012/19/EU of the European Parliament and of the Council on Waste Electrical and Electronic Equipment (WEEE).

**1.0 Items Requiring Selective Treatment**

- 1.1 Items listed below are classified as requiring selective treatment.  
 1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.  
 1.3 Quantities vary by product configuration

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	11
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	Quantity varies by product configuration and power supply model selected	4
External electrical cables and cords	Quantity depends on number of power supplies, networking devices, and I/O devices	4-12
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0

Item Description	Notes	Quantity of items included in product
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
#1 Phillips Driver Bit	P1
#2 Phillips Driver Bit	P2
T10 Torx Driver Bit	T10
T20 Torx Driver Bit	T20

## 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove server from rack
2. Remove top & Bottom covers.
3. Remove blue screw and cable from rear of Base IO tray
4. Remove base IO tray
5. Remove battery
6. Remove power supplies
7. Remove power supply cover
8. Remove the 3 capacitors from each power supply.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

Attachment 1 & 2 – Location of Electrolytic Capacitors in PSU

Attachment 3 – Location of Coincell Battery

**Attachment 1:**



**Attachment 2:**



**Attachment 3:**

